

SOT1107-1

plastic thin fine-pitch ball grid array package; 296 balls

8 February 2016

Package information

1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	TFBGA296
Package type industry code	TFBGA296
Package style descriptive code	TFBGA (thin fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	7-8-2008

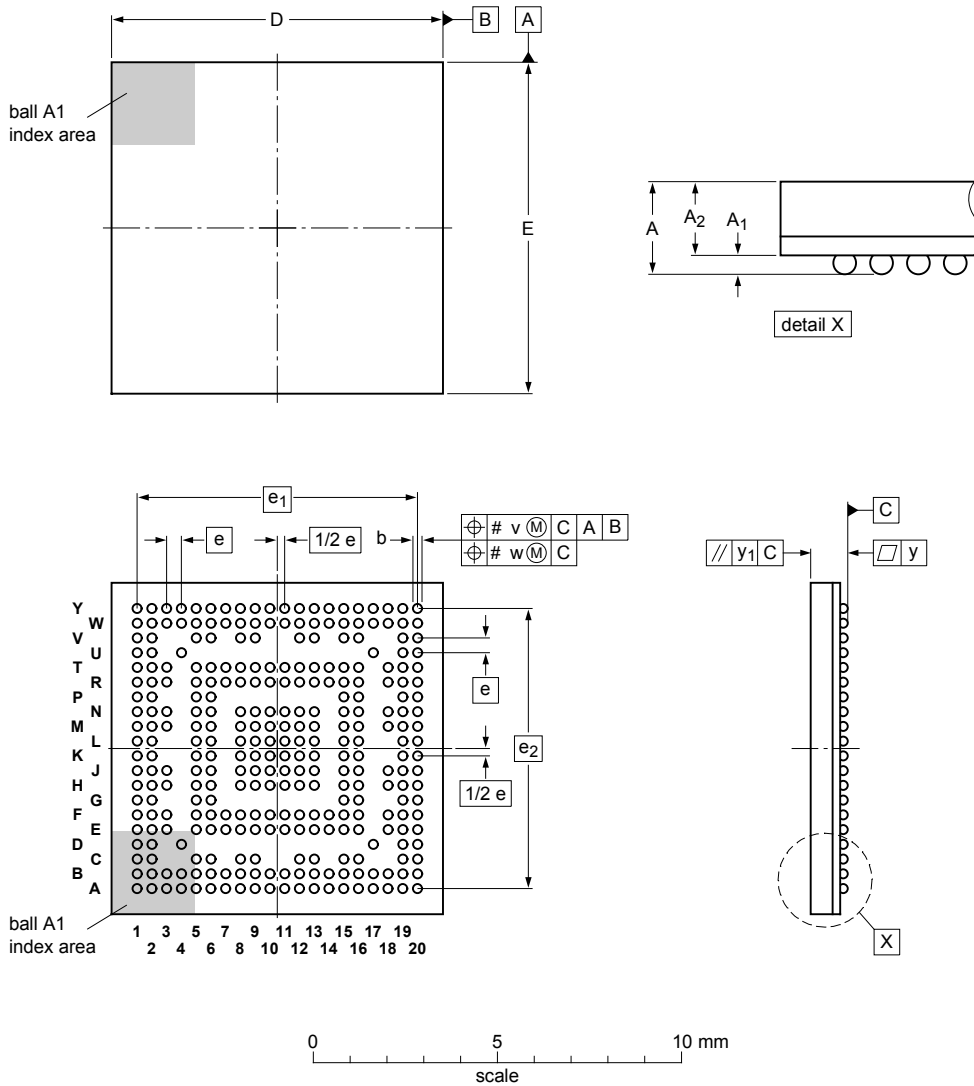
Table 1. Package summary

Symbol	Parameter	Min	Typ	Nom	Max	Unit
D	package length	8.9	-	9	9.1	mm
E	package width	8.9	-	9	9.1	mm
A	seated height	0.9	-	1.01	1.15	mm
A ₂	package height	0.75	-	0.81	0.9	mm
n ₂	actual quantity of termination	-	-	296	-	



2. Package outline

TFBGA296: plastic thin low profile fine-pitch ball grid array package; 296 balls SOT1107-1



DIMENSIONS (mm are the original dimensions)

UNIT		A	A ₁	A ₂	b	D	E	e	e ₁	e ₂	v	w	y	y ₁
mm	max	1.15	0.25	0.90	0.30	9.1	9.1	0.4	7.6	7.6	0.15	0.08	0.08	0.1
	nom	1.01	0.20	0.81	0.25	9.0	9.0							
	min	0.90	0.15	0.75	0.20	8.9	8.9							

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT1107-1						08-06-25 08-08-07

Fig. 1. Package outline TFBGA296 (SOT1107-1)

3. Soldering

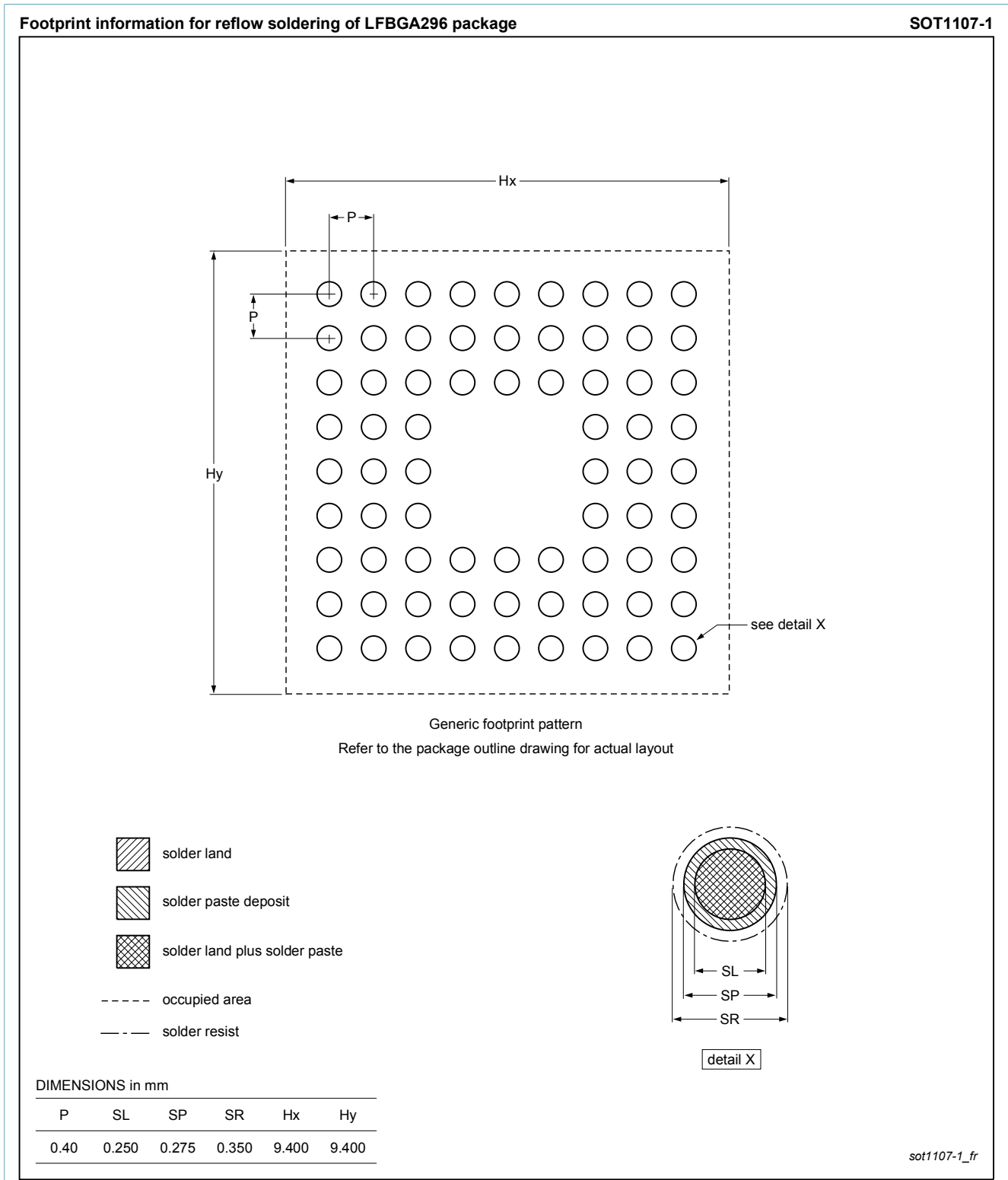


Fig. 2. Reflow soldering footprint for TFBGA296 (SOT1107-1)

4. Legal information

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